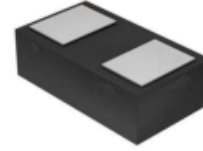


1. Features

- Capacitance: 15pF(typ.)
- Reverse Working Voltage: 5V
- IEC 61000-4-2 (ESD Air): ±25KV
IEC 61000-4-2 (ESD Contact): ±25KV
IEC 61000-4-5 (Lightning 8/20µs): 7A

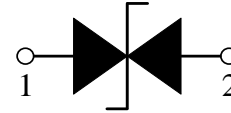
2. Pin Description



3. Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

4. Schematic Diagram



5. Limiting Values(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±25	kV
		IEC 61000-4-2; Air Discharge	-	±25	kV
P _{PP}	Peak Pulse Power	t _P = 8/20 µs	-	70	W
I _{PPM}	Rated Peak Pulse Current	t _P = 8/20 µs	-	7	A
T _A	Ambient Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-55	150	°C

6. Electrical Characteristics(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V _{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	5.0	V
V _{BR}	Breakdown Voltage	I _R = 1mA; T _A = 25 °C	5.6	6.5	8.4	V
I _R	Reverse Leakage Current	V _{RWM} = 5V; T _A = 25 °C	-	-	0.1	µA
V _C	Clamping Voltage	I _{PP} =1A, t _P =8/20µs	-	-	6	V
		I _{PP} =7A, t _P =8/20µs	-	-	10	V
C _J	Junction Capacitance	V _R = 0V, f = 1 MHz	-	15	18	pF

7. Typical Characteristics

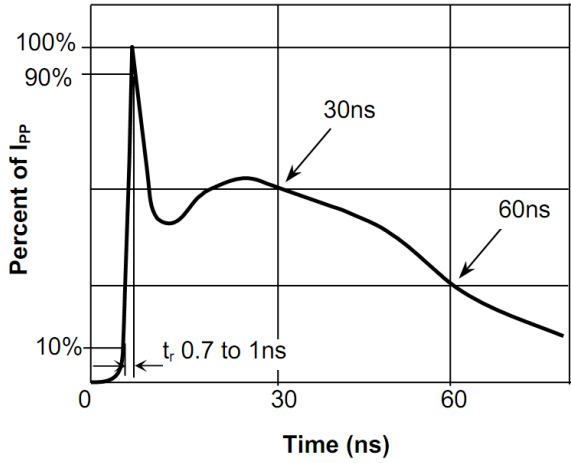


Fig.1 Pulse Waveform-ESD (IEC61000-4-2)

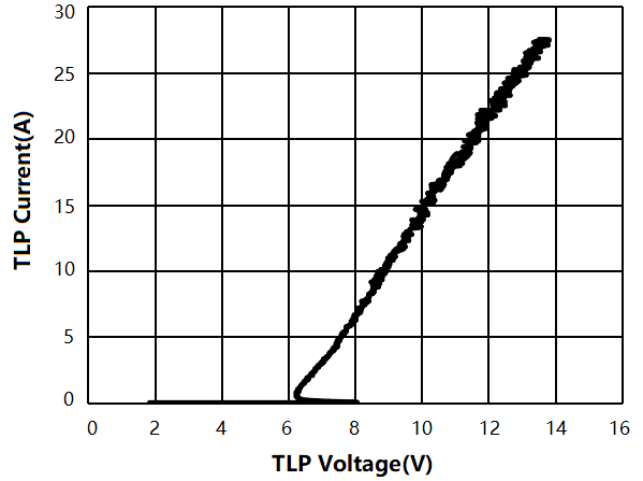


Fig.2 Transmission Line Pulse (TLP)

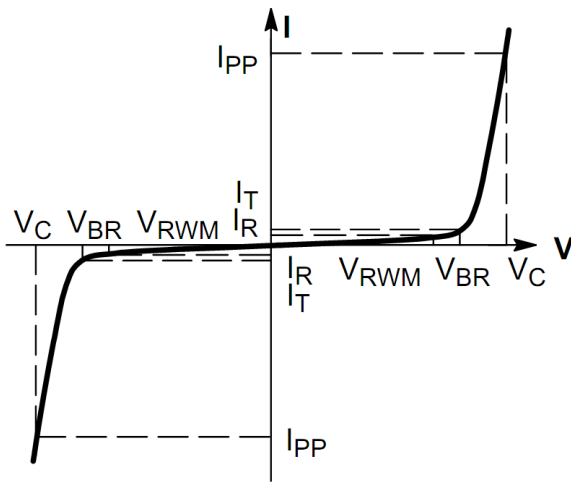


Fig.3 V-I Characteristics for Bidirectional Diode

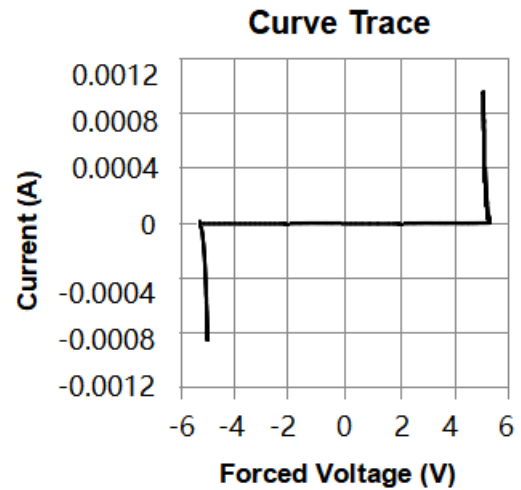


Fig.4 IV Curve

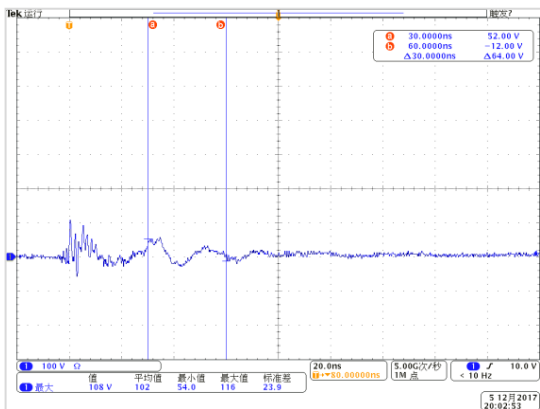


Fig.5 Clamping Voltage at IEC61000-4-2 +8kV Pulse Waveform

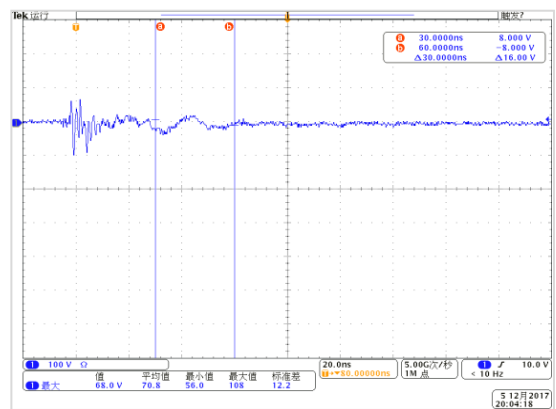
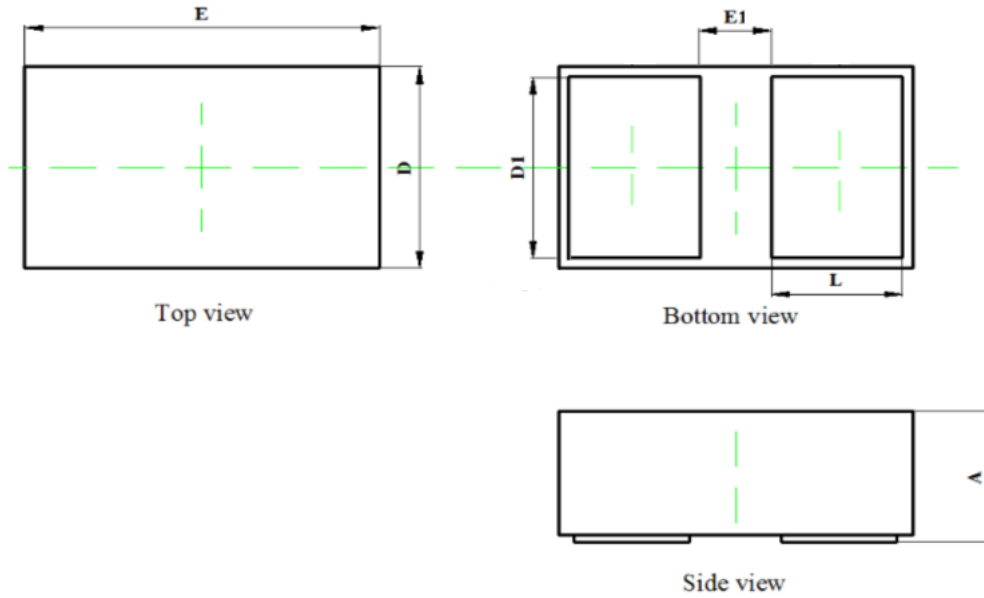


Fig.6 Clamping Voltage at IEC61000-4-2 -8kV Pulse Waveform

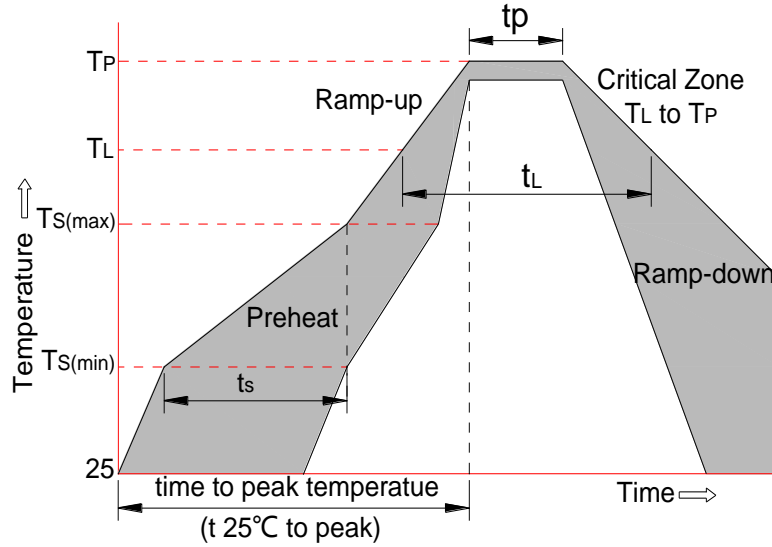
8. Package Outline Dimensions

DFN0603 Package Outline



Symbol	Dimensions In Millimeters		
	Min	Typical	Max
A	0.28	0.30	0.32
D	0.29	0.32	0.35
E	0.59	0.62	0.65
D1	0.22	0.25	0.28
E1	0.15	0.18	0.21
L	0.16	0.19	0.22

9. Soldering Parameters



Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C